

Model 899-1 R****

1.21 gms

Breakdown of component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name. (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass. (g)
Alumina Substrate	Alumina	Aluminum Oxide	1344-28-1	0.61362
		Silica	7631-86-9	0.020441
		Magnesium Oxide	1309-48-4	0.002811
		Other		0.0023
Thick Film with Alumina Substrate	Marking Glass	Lead Oxide	1317-36-8	0.000192
Thick Film with Alumina Substrate	Termination	Silver	7440-22-4	0.005072
Thick Film with Alumina Substrate	Resistor	Frit Lead Bearing	65997-18-4	0.00168
		Ruthenium Dioxide	12036-10-1	0.0007
		Lead Ruthenium Oxide	37194-88-0	0.00042
		Manganese Oxide	1313-13-9	0.000028
Thick Film with Alumina Substrate	Glass	Antimony trioxide	1309-64-4	0.000028
		Lead Oxide	1317-36-8	0.001589
Ceramic cover	Oxides	Chromium 11 Oxide	1308-38-9	0.000199
		Al2O3	1344-28-1	0.190
LEAD FRAME	Copper (K65) electroplated with tin	SiO2	14808-60-7	0.006
		MgO	1309-48-4	0.004
		Copper	7440-50-8	0.174774
		Bisphenol-A Type Epoxy Resin	25068-38-6	0.02975
		Elastomer Modified Resin	68909-14-8	0.0175
		Oxirane,[(2-Methylphenoxy)Methyl]	2210-79-9	0.00875
Epoxy		Aluminium Hydroxide	21645-51-2	0.02975
		Amorphous Silicon Dioxide	7631-86-9	0.000875
		Carbon Black	1333-86-4	0.000875
		Tin	7440-31-5	0.033775
		Silver	7440-22-4	0.001225
Solder paste	Sn96.5Ag3.5			
Other				0.05946